

Parameter	DTr1 and DTr2
$V_{CC}$	-50V
$I_{C(MAX.)}$	-100mA
$R_1$	10k $\Omega$
$R_2$	10k $\Omega$

### ●Features

- 1)Two DTA114E chips in UMT and SMT packages.
- 2)Mounting cost and area can be cut in half.

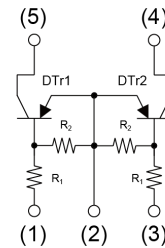
### ●Outline

SOT-353	SOT-25
UMA9N (UMT5)	FMA9A (SMT5)

### ●Inner circuit

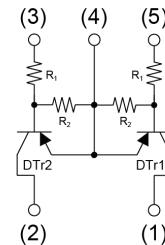
#### UMA9N

- (1) DTr1 IN(Base)
- (2) DTr1 / DTr2 GND(Emitter)
- (3) DTr2 IN(Base)
- (4) DTr2 OUT(Collector)
- (5) DTr1 OUT(Collector)



#### FMA9A

- (1) DTr1 OUT(Collector)
- (2) DTr2 OUT(Collector)
- (3) DTr2 IN(Base)
- (4) DTr1 / DTr2 GND(Emitter)
- (5) DTr1 IN(Base)



### ●Application

INVERTER, INTERFACE, DRIVER

### ●Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
UMA9N	SOT-353 (UMT5)	2021	TR	180	8	3000	A9
FMA9A	SOT-25 (SMT5)	2928	T148	180	8	3000	A9

● **Absolute maximum ratings** ( $T_a = 25^\circ\text{C}$ )

<For DTr1 and DTr2 in common>

Parameter		Symbol	Values	Unit
Supply voltage		$V_{CC}$	-50	V
Input voltage		$V_{IN}$	-40 to 10	V
Output current		$I_O$	-50	mA
Collector current		$I_{C(MAX)}^{*1}$	-100	mA
Power dissipation	UMA9N	$P_D^{*2*3}$	150	mW/Total
	FMA9A	$P_D^{*2*4}$	300	
Junction temperature		$T_j$	150	$^\circ\text{C}$
Range of storage temperature		$T_{stg}$	-55 to +150	$^\circ\text{C}$

● **Electrical characteristics** ( $T_a = 25^\circ\text{C}$ )

<For DTr1 and DTr2 in common>

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input voltage	$V_{I(off)}$	$V_{CC} = -5V, I_O = -100\mu\text{A}$	-	-	-0.5	V
	$V_{I(on)}$	$V_O = -0.3V, I_O = -10\text{mA}$	-3	-	-	
Output voltage	$V_{O(on)}$	$I_O = -10\text{mA}, I_I = -0.5\text{mA}$	-	-100	-300	mV
Input current	$I_I$	$V_I = -5V$	-	-	-880	$\mu\text{A}$
Output current	$I_{O(off)}$	$V_{CC} = -50V, V_I = 0V$	-	-	-500	nA
DC current gain	$G_1$	$V_O = -5V, I_O = -5\text{mA}$	30	-	-	-
Input resistance	$R_1$	-	7	10	13	$\text{k}\Omega$
Resistance ratio	$R_2/R_1$	-	0.8	1.0	1.2	-
Transition frequency	$f_T^{*1}$	$V_{CE} = -10V, I_E = 5\text{mA}, f = 100\text{MHz}$	-	250	-	MHz

\*1 Characteristics of built-in transistor.

\*2 Each terminal mounted on a reference land.

\*3 120mW per element must not be exceeded.

\*4 200mW per element must not be exceeded.

● **Electrical characteristic curves** ( $T_a = 25^\circ\text{C}$ )  
 <For DTr1 and DTr2 in common>

Fig.1 Input Voltage vs. Output Current  
 (ON Characteristics)

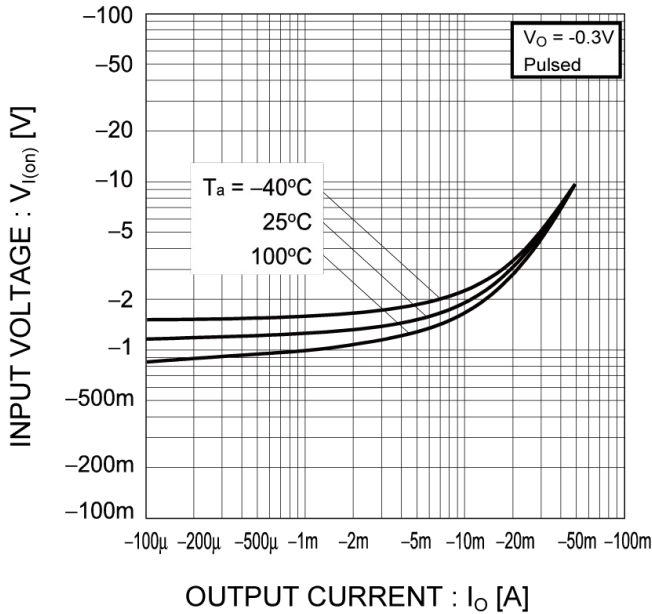


Fig.2 Output Current vs. Input Voltage  
 (OFF Characteristics)

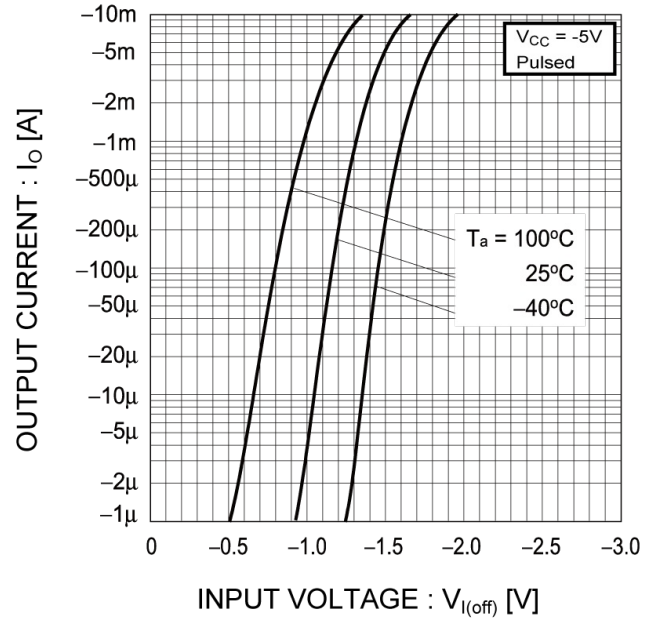


Fig.3 Output Current vs. Output Voltage

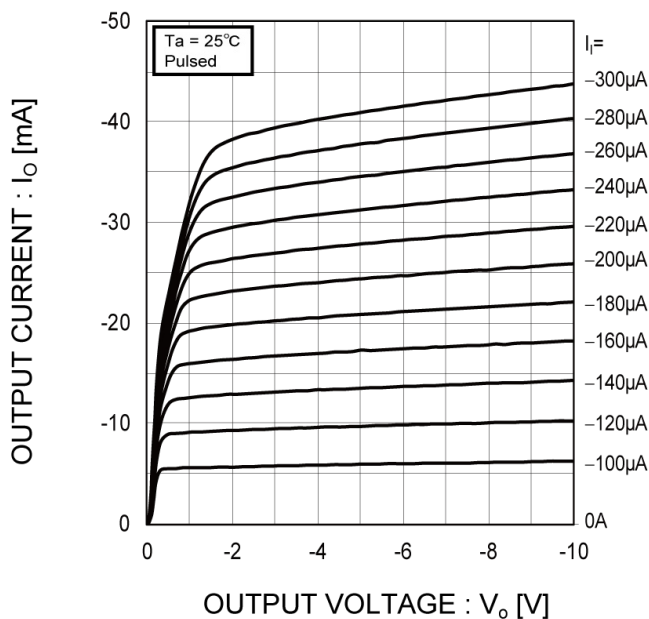
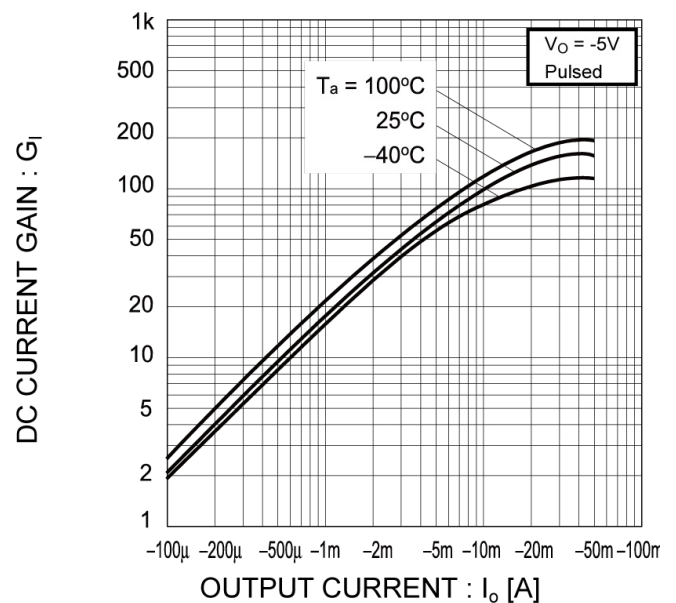


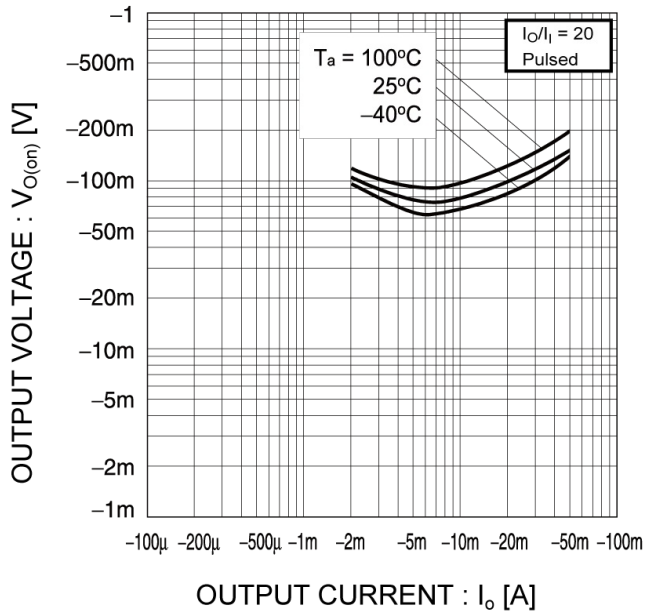
Fig.4 DC Current Gain vs. Output Current



● **Electrical characteristic curves** ( $T_a = 25^\circ\text{C}$ )

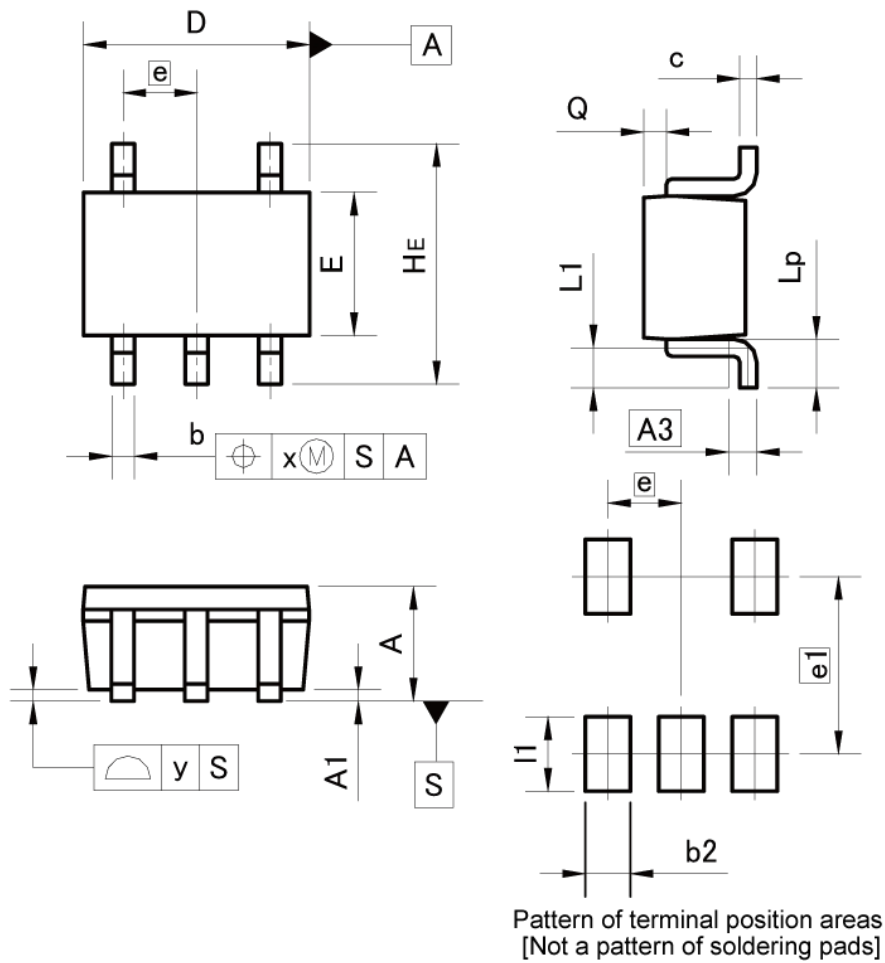
<For DTr1 and DTr2 in common>

Fig.5 Output Voltage vs. Output Current



●Dimensions

SOT-353  
SC-88A  
(UMT5)



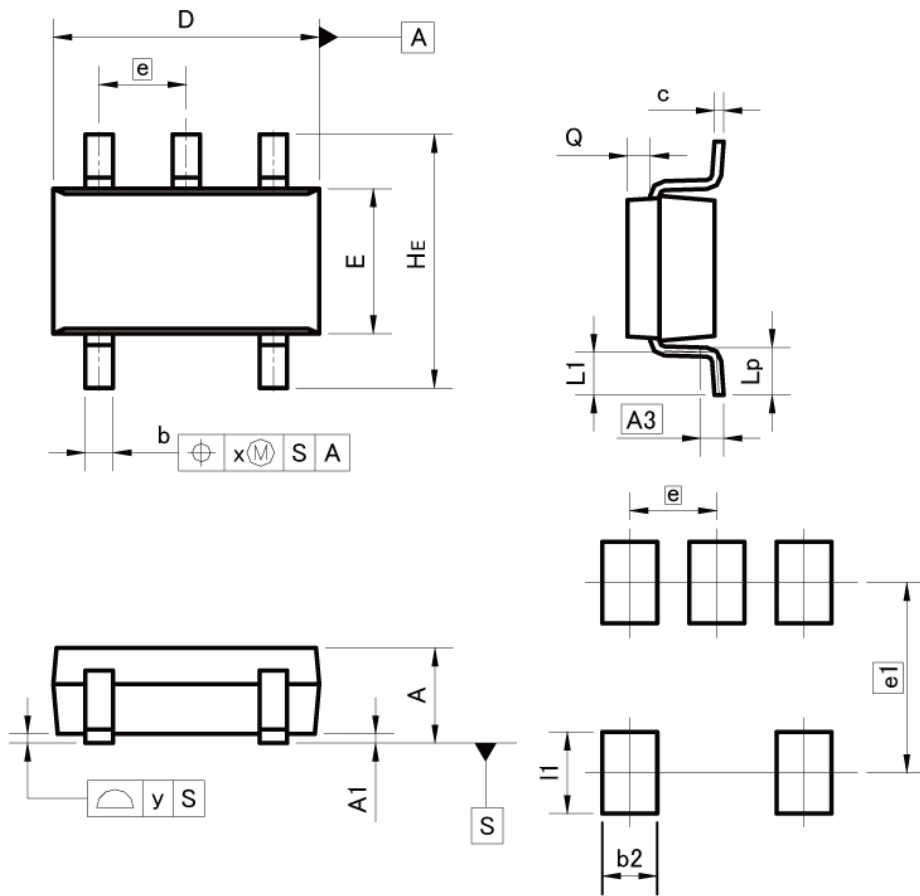
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.15	0.30	0.006	0.012
c	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.40	-	0.016
e1	1.55		0.061	
l1	-	0.65	-	0.026

Dimension in mm/inches

●Dimensions

SOT-25  
SC-74A  
(SMT5)



Pattern of terminal position areas  
[Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.25	0.40	0.010	0.016
c	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
e	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x	-	0.20	-	0.008
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.60	-	0.024
e1	2.10		0.083	
l1	-	0.90	-	0.035

Dimension in mm/inches

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